REMARKS

Upon entry of this Preliminary Amendment into the above-identified Continuing Application, claims 8-22 will be under active consideration in the application.

Claims 1-7 have been cancelled without prejudice. Applicants have added new claims 8-22 so as to define further patentable aspects of the invention. Applicants have also amended the specification to correct informalities identified in the parent application Serial No. 09/310,397. No new matter has been entered into the application as a result of these additions to the application. Claims 8-22 are allowable. Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Accordingly, Applicants respectfully request the issuance of a Notice of Allowability for this case. Early and favorable consideration is respectfully requested.

Respectfully submitted,

Dated: <u>5/9/</u>

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Docket No.: H1799-00071 - 8 -

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Version with markings to show changes made.

IN THE SPECIFICATIONS

At page 1, on the line between the title and "§1. Background of the Invention", a claim of priority was added as follows:

- - This application is a continuation application of copending U.S. Application Serial No. 09/310,397, filed on May 12, 1999. - -.

On page 6, starting on line 11, the following paragraph was replaced as follows:

- - Fig. 3 is a plan view of an internal surface of the contact plate of the preferred embodiment of the invention showing the region of the capillary wick constructed of sintered higher heat conductivity powder. - -

On page 8, starting on line 3, the following paragraph was replaced as follows:

- - In the present invention, heat pipe 10 also has capillary wick pillars 32 which bridge the space between contact plate 18 and cover plate 20. Pillars 32 thereby interconnect cover plate 20 [16] and contact plate 18 [14] with continuous capillary wick. This geometry assures that, even if heat pipe 10 is oriented so that cover plate 20 [16] is lower than contact plate 18 [14], liquid condensed upon inner surface 34 of cover plate 20 will still be in contact with capillary pillars 32. The liquid will therefore be moved back to inner [raised] surface 28 which functions as the evaporator because it is in contact with a heat generating integrated circuit (not shown). Capillary pillars 32 are wrapped around and supported by depressions 26, which prevents the structurally weaker capillary pillars 32 from suffering any damage. - -

On page 10, starting on line 10, the following paragraph was replaced as follows:

Docket No.: H1799-00071 - 9 -

- The only differences between heat pipe 11 of Fig. 2 and heat pipe 10 of Fig. 1 are that finned heat sink 16 is not shown in Fig. 2, lips 22 and 24 are slightly longer in Fig. 2 to accommodate holes 48, and hole 50 is shown. In fact, through holes 12 shown in Fig. 1 [12] are also included in Fig. 2. Although it is unlikely that holes 12, holes 48, and hole 50 would be used in the same assembly, manufacturing economies may make it desirable to produce all the holes in every heat pipe so that the same heat pipe heat spreader can be used with different configurations of finned heat sinks. The unused sets of holes have no effect on the operation or benefits of the invention. - -

IN THE CLAIMS

Claims 1-7 have been canceled without prejudice.

Claims 8-22 have been added.

Docket No.: H1799-00071 - 10 -